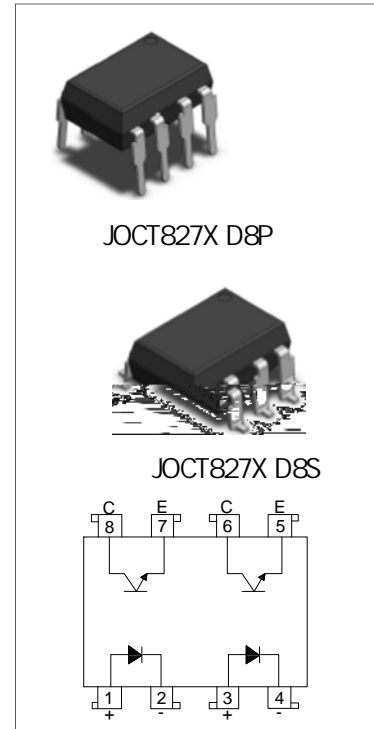


### DESCRIPTION:

The products are transistor opto-couplers in a plastic DIP8 package with different lead forming options. The device is a photoelectric coupler composed of light-emitting diode and phototransistor. The products are widely used in switching power supply, intelligent meter, industrial control, measuring instruments, office equipment such as copiers, household appliances: such as air conditioners, fans, water heaters, etc.

### MAIN FEATURES

- High isolation 5000 VRMS
- Operating temperature range -55°C to 110°C
- RoHS & REACH Compliance
- HBM: H3A; MM: M4; CDM:C3
- CQC approved
- VDE approved
- UL approved



### ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	$I_F$	50	mA
	Peak Forward Current	$I_{FP}$	1	A
	Reverse Voltage	$V_R$	6	V
	Power Dissipation	$P_D$	75	mW
Output	Collector-emitter Voltage	$V_{CEO}$	80	V
	Emitter-collector Voltage	$V_{ECO}$	6	V
	Collector Current	$I_C$	50	mA
	Power Dissipation	$P_C$	150	mW
Total Power Dissipation		$P_{tot}$	225	mW
Isolation Voltage		$V_{iso}$	5000	Vrms
Operating Temperature		$T_{opr}$	-55~+110	
Junction Temperature		$T_j$	125	
Storage Temperature		$T_{stg}$	-55~+125	
Soldering Temperature		$T_{sol}$	260	

NOTE1: 1  $\mu$ s pulse    NOTE2: AC for 1minute, R.H.=40-60%**ELECTRICAL CHARACTERISTICS** (Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	$V_F$	$I_F=10\text{mA}$	-	1.2	1.5	V
	Reverse Current	$I_R$	$V_R=6\text{V}$	-	-	1	$\mu\text{A}$
	Terminal Capacitance	$C_t$	$V=0,$ $f=1\text{MHz}$	-	30	250	pF
Output	Collector-Emitter dark current	$I_{CEO}$	$V_{CE}=20\text{V},$ $I_F=0$	-	-	50	nA
	Collector-Emitter breakdown voltage	$BV_{CEO}$	$I_C=0.1\text{mA}$ $I_F=0$	80	-	-	V
	Emitter-Collector breakdown voltage	$BV_{ECO}$	$I_E=0.1\text{mA}$ $I_F=0$	6	-	-	V
	Current transfer ratio	CTR	$I_F=5\text{mA}$ $V_{CE}=5\text{V}$	80	-	600	%

Collector-Emitter  
Saturation V

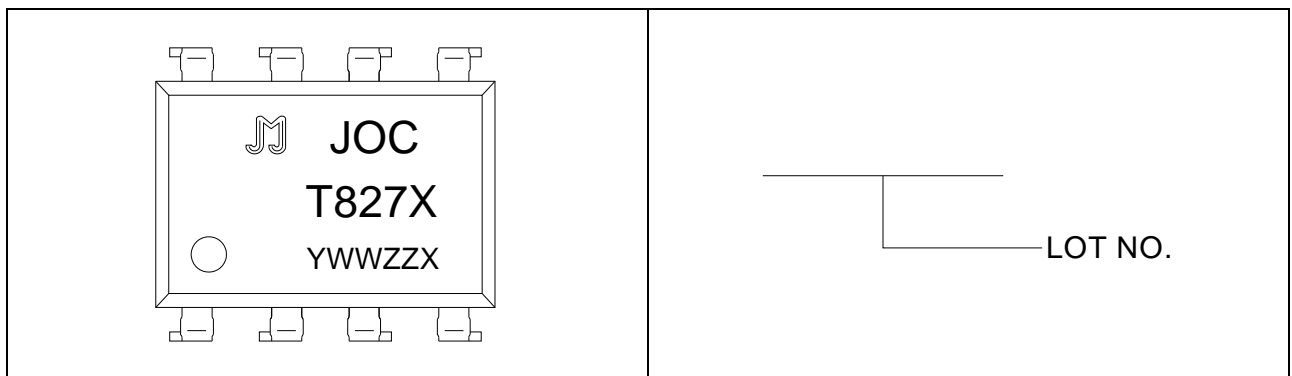
Transfer  
Characteristics

ORDERING INFORMATION

<p><b>J</b></p> <p>JieJie Microelectronics Co., Ltd.</p>	<p><b>OC</b></p> <p>Opto Coupler</p>	<p><b>T</b></p> <p>Transistor</p>	<p><b>827</b></p> <p>Marketization Model</p>	<p><b>C</b></p> <p>CTR Rank:A/B/C/D/E/Q/None</p>	<p><b>-D8P/S</b></p> <p>P:DIP8 S:SMD8</p>	<p><b>/</b></p> <p>S:T3 L:T4</p>
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Packing Quantity	
Option	Quantity
DIP	0Units/Tube
SMD	1200Units/Reel

MARKING

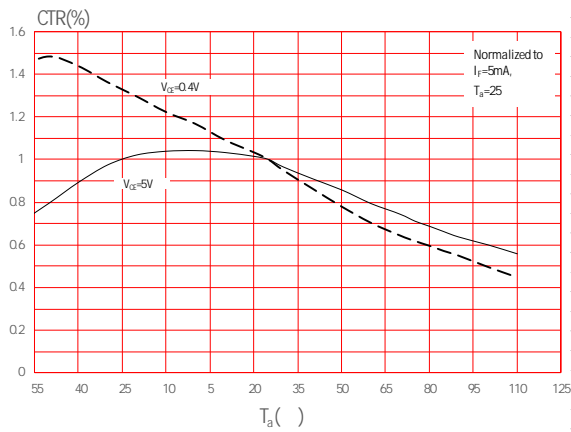


## Characteristics Curves

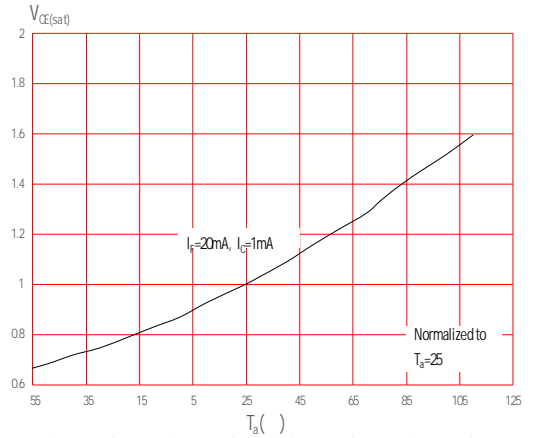
**FIG.1:** Max. Allowable LED Forward Current vs.  
Ambient Temperature

**Ambierature**

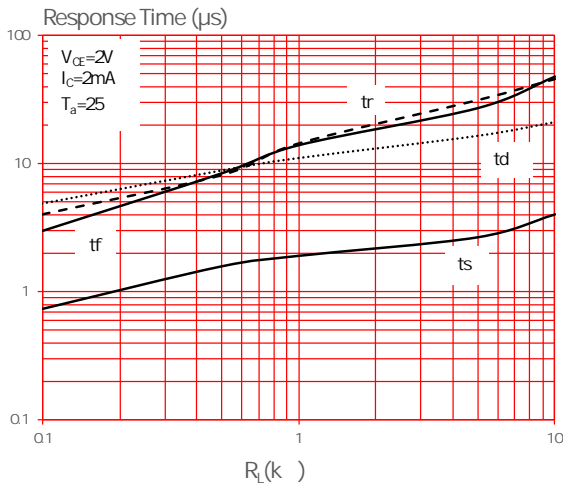
**FIG.7:** Normalized Current Transfer Ratio vs. Ambient Temperature



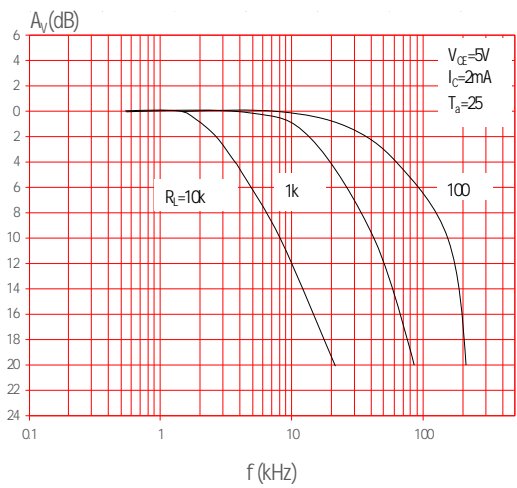
**FIG.8:** Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature



**FIG.9:** Response Time vs. Load Resistance



**FIG.10:** Frequency Response



Test Circuits

FIG.11: Test Circuits of Response Time

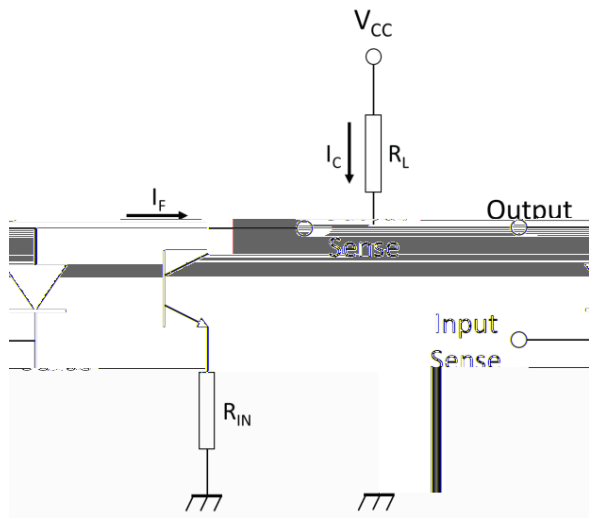


FIG.12: Curves of Response Time

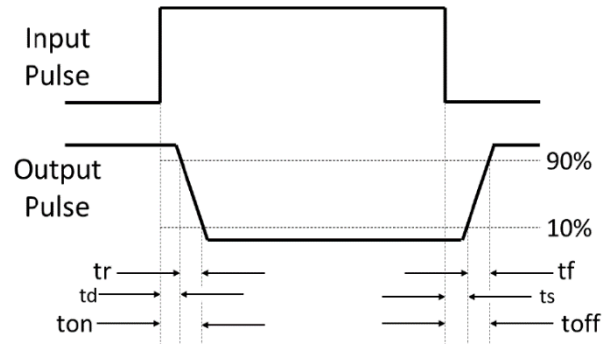
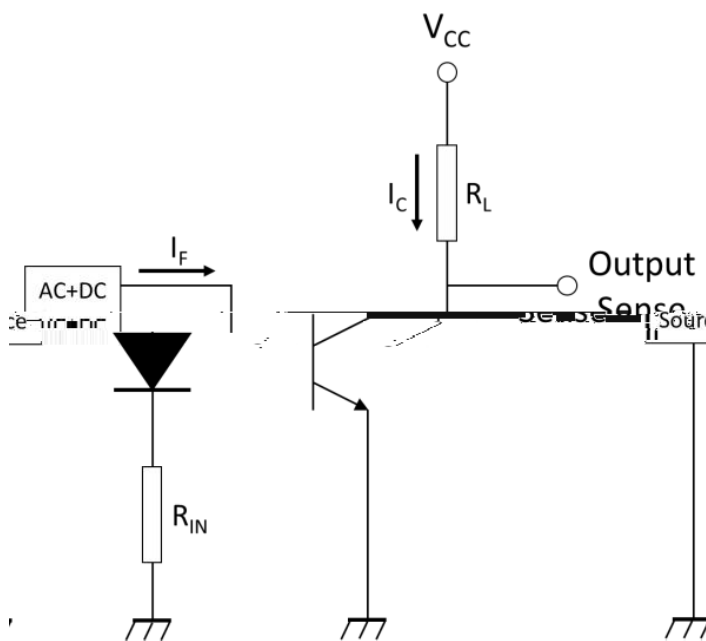
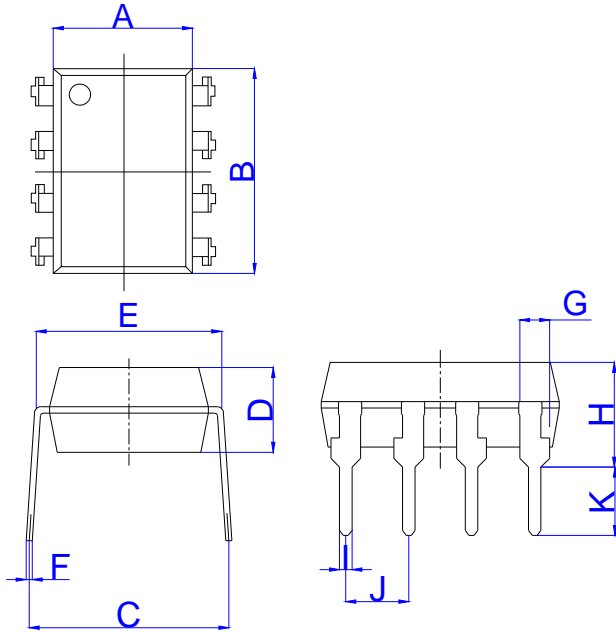


FIG.13: Test Circuits of Frequency Response



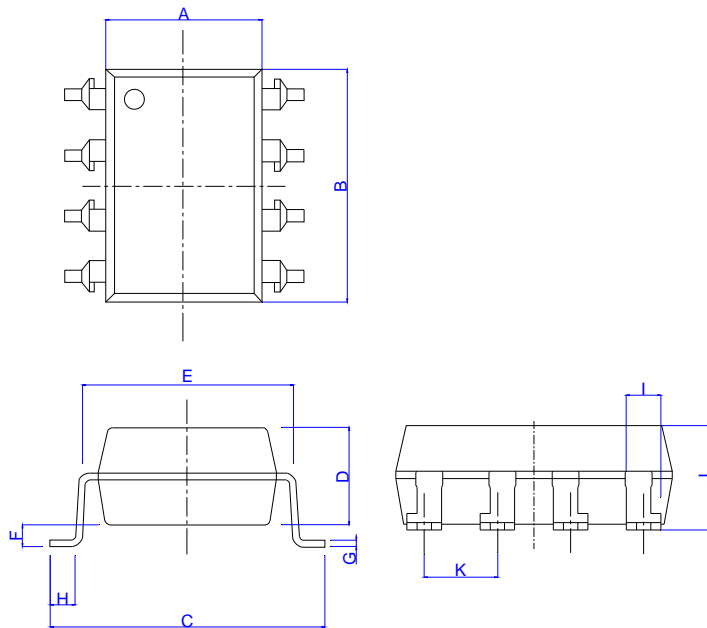
Package Dimension (Unit: mm)

Standard DIP Type:



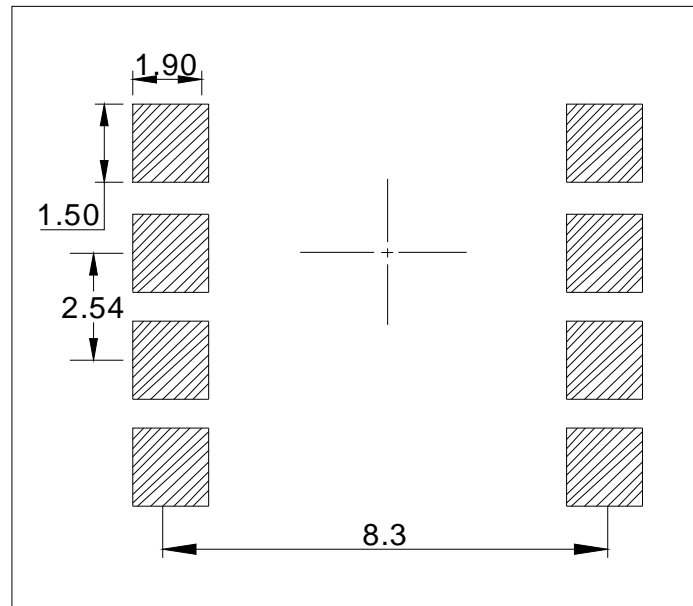
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

Option SMD Type:



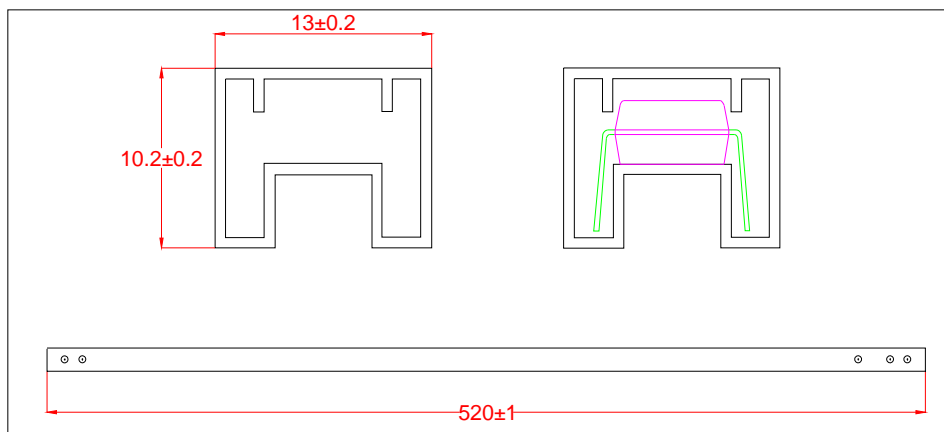
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



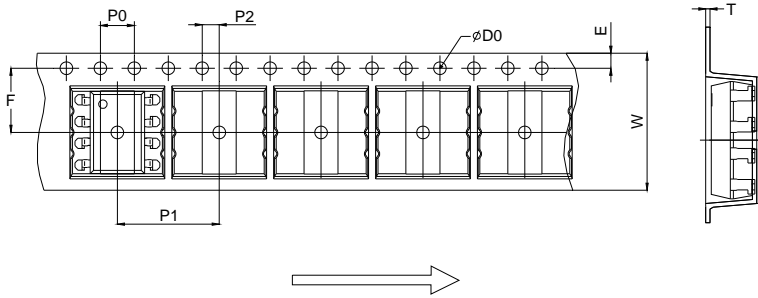
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Standard DIP



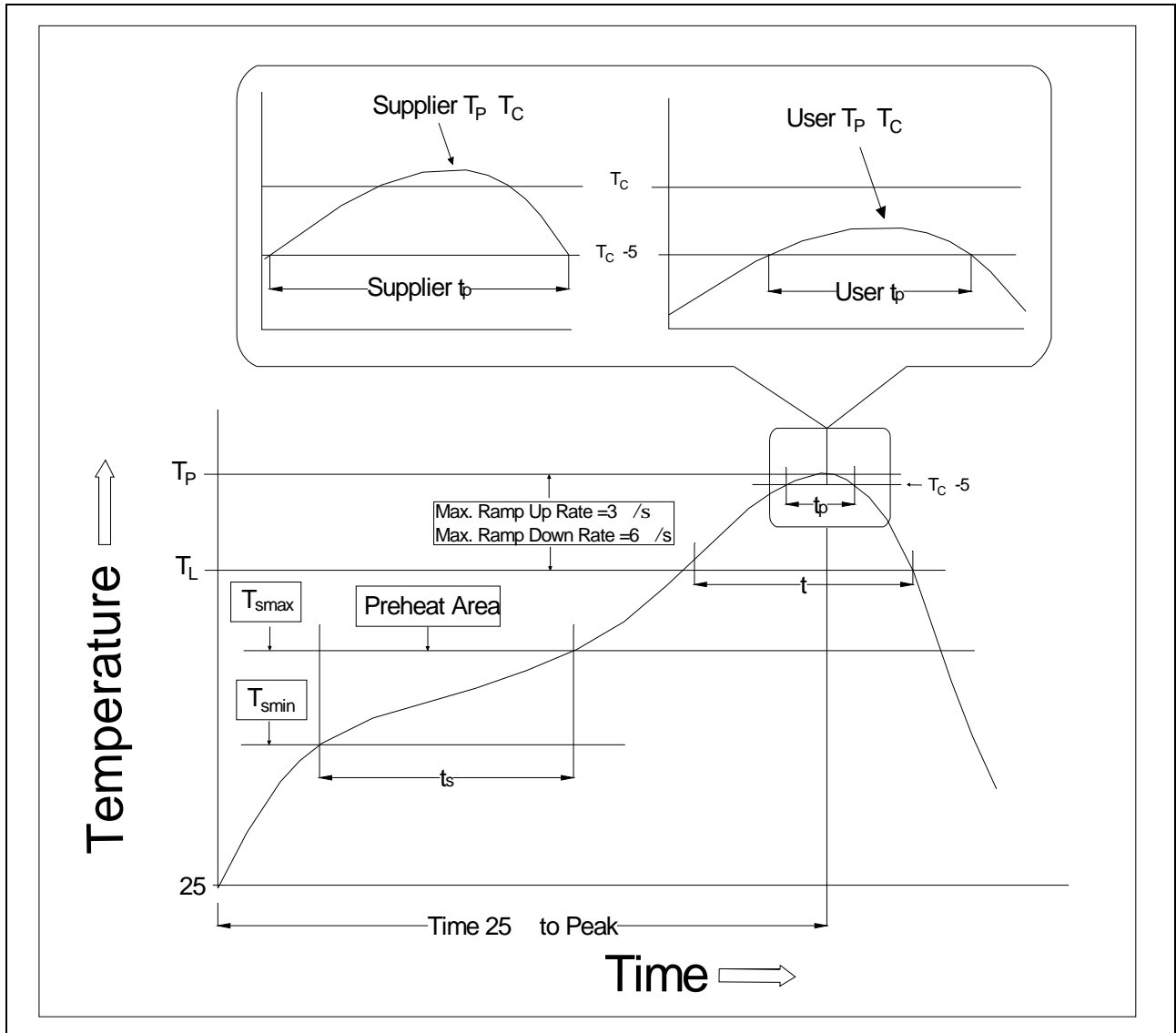
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S/L



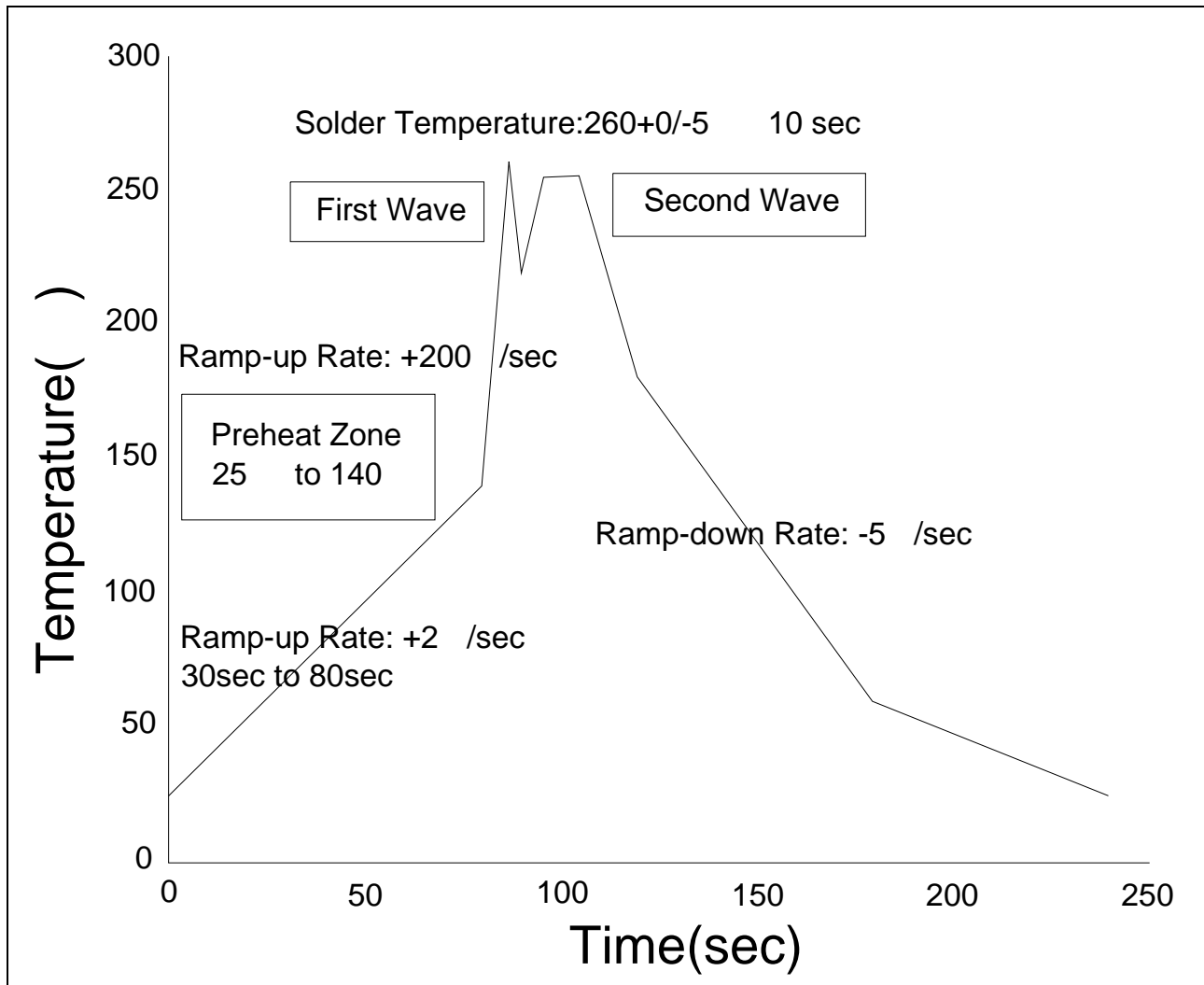
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	11.90	12.00	12.10	0.469	0.472	0.476
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
T	0.35	0.40	0.45	0.014	0.016	0.018
W	15.90	16.00	16.20	0.626	0.630	0.638

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	100	150
Temperature Max. (T <sub>smax</sub> )	150	200
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3 °C/second max.	3 °C/second max.
Liquidus Temperature (T <sub>L</sub> )	183	217
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (t <sub>P</sub> ) within 5 °C of 260	20 seconds	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON


Soldering Temperature	360± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;  
Recommend storage humidity: <60%;  
MSL level: MSL 1

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